



Material Composition Declaration

EPC2059

Company Name	Efficient Power Conversion (EPC)	Issue Date:	11/10/2020
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	5.9 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	4.5192	76.8680	79.8617	768680
	Silicon oxide	7631-86-9	0.0150	0.2557		2557
	Silicon nitride	12033-89-5	0.0109	0.1852		1852
	Gallium nitride	25617-97-4	0.0291	0.4957		4957
	Aluminum	7429-90-5	0.0610	1.0382		10382
	Aluminum nitride	24304-00-5	0.0070	0.1194		1194
	Titanium	7440-32-6	0.0008	0.0132		132
	Titanium nitride	25583-20-4	0.0059	0.1011		1011
	Copper	7440-50-8	0.0020	0.0346		346
	Tungsten	7440-33-7	0.0046	0.0787		787
	Polyimide		0.0395	0.6719	6719	
Under Bump Metal	Titanium	7440-32-6	0.0006	0.0101	0.1104	101
	Copper	7440-50-8	0.0059	0.1003		1003
Solder Bump	Copper	7440-50-8	0.0590	1.0028	20.0279	10028
	Nickel	7440-02-0	0.0352	0.5982		5982
	Tin	7440-31-5	1.0639	18.0953		180953
	Silver	7440-22-4	0.0195	0.3317		3317
Sum in total:			5.8792	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.